





# SPECIFICATION FOR APPROVAL

CUSTOMER	
NOMINAL FREQUENCY	8.000000 MHz
PRODUCT TYPE	TYPE F9 5.0x3.2 GLASS SEALED CRYSTAL
SPEC. NO. ( P/N )	F90800031Q
CUSTOMER P/N	
ISSUE DATE	November 29, 2017
VERSION	A

APPROVED	PREPARED	QA
Brenda	Clane	Dong Jang

# **Diodes Incorporated**

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- \*RoHS Exemption
- \*HF-Halogen Free
- \*REACH Compliant
- \*AEC-Q200 Compliant

E0-R-4-014 Rev. F

F90800031Q

VER. A 29-Nov-17

# **VERSION HISTORY**

Verision No.	Verision Date	Description	Notes
Α	Nov.29,2017	Initial Release	



## F90800031Q

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### **ELECTRICAL SPECIFICATIONS**

Item	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	8.000000	MHz	
Mode of Oscillation	MO	AT Cut-Fundamental		
Calibration Load Capacitance	CL	18	pF	
Calibration Tolerance	FL	±20	ppm	at 25°C±3°C
Operating Temperature Range	TR	-40 to +85	°C	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	±20	ppm	Reference to the Frequency at 25°C
Operating Drive Level		10	μW	
Maximum Drive Level		100	μW	
Equivalent Series Resistance	ESR	140	Ω	Max
Shunt Capacitance	C0	5	pF	Max.
Aging at 25°C		±3	ppm	Max, 1st year
Storage Temperature		-55 to +125	°C	
Insulation Resistance		500	МΩ	Min



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#### **AEC-Q200 RELIABILITY TEST SPECIFICATIONS:**

#### 1. Initial

- 1.1 Physical Dimensions: JESD22, Method JB1-100
- 1.2 External Visual: MIL-STD-883, Method 2009
- 1.3 Freq. Vs. Temperature: Per Specification/Datasheet

#### 2. Mechanical

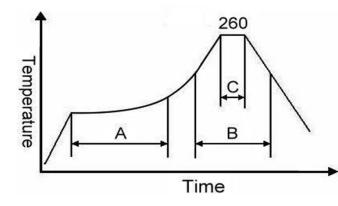
- 2.1 Mechanical Shock: MIL-STD-202 Method 213
- 2.2 Vibration: MIL-STD-202 Method 204
- 2.3 Solderability: J-STD-002
- 2.4 Board Flex: AEC Q200-005
- 2.5 Terminal Strength (SMD): AEC Q200-006

#### 3.Environmental

- 3.1 Temp Cycle: JESD22, Method JA-104
- 3.2 Resistance to Solder Heat: MIL-STD-202 Method 210
- 3.3 High Temperature Operating Life: MIL-STD-202, Method 108
- 3.4 High Temp. Exposure: MIL-STD-202, Method 108
- 3.5 High Temp. & High Humidity: MIL-STD-202, Method 103
- 3.6 Thermal Shock: MIL-STD-202, Method 107

#### SUGGESTED IR REFLOW PROFILE

\*As per IPC-JEDEC J-STD-020D



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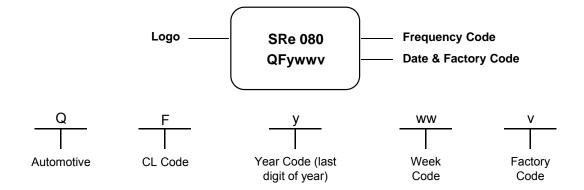
	Stage	Temperature	Time
Α	Preheat	150~200°C	60~120 Sec
В	Primary Heat	217°C	60~150 Sec
С	Peak	260°C	10 Sec



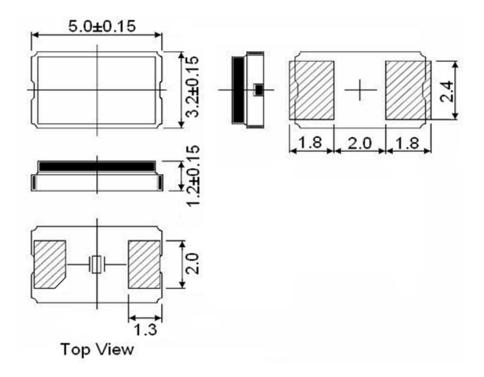
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#### **MARKING**



### MECHANICAL DRAWINGS (Scale: None. Dimensions are in mm.)

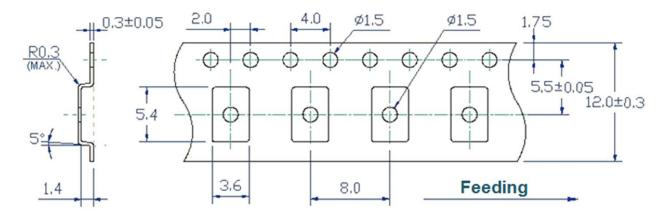


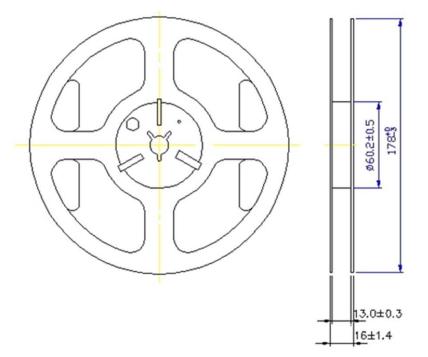
Note:

Pin shape is only for reference, and the Pin with chamfer or without chamfer is based on the real product.



### Tape & Reel





- 1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
- 2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

